High Voltage Transistor Surface Mount

NPN Silicon

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage (Open Base)	V _{CEO}	300	Vdc
Collector-Base Voltage (Open Emitter)	V _{CBO}	300	Vdc
Emitter-Base Voltage (Open Collector)	V _{EBO}	6.0	Vdc
Collector Current (DC)	I _C	500	mAdc
Total Power Dissipation @ T _A = 25°C (Note 1)	P _D	1.5	W
Storage Temperature Range	T _{stg}	-65 to 150	°C
Junction Temperature	TJ	150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

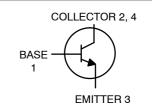
1. Device mounted on a FR-4 glass epoxy printed circuit board 1.575 in x 1.575 in x 0.0625 in; mounting pad for the collector lead = 0.93 sq in.



ON Semiconductor®

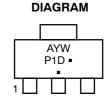
http://onsemi.com

SOT-223 PACKAGE NPN SILICON HIGH VOLTAGE TRANSISTOR SURFACE MOUNT





SOT-223 CASE 318E STYLE 1



MARKING

P1D = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristics	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage (Note 2) (I _C = 1.0 mAdc, I _B = 0)	V _(BR) CEO	300	_	Vdc
Collector-Base Breakdown Voltage (I _C = 100 μAdc, I _E = 0)	V _{(BR)CBO}	300	_	Vdc
Emitter-Base Breakdown Voltage ($I_E = 100 \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	6.0	_	Vdc
Collector-Base Cutoff Current $(V_{CB} = 200 \text{ Vdc}, I_E = 0)$	I _{CBO}	_	0.1	μAdc
Emitter-Base Cutoff Current $(V_{BE} = 6.0 \text{ Vdc}, I_C = 0)$	I _{EBO}	_	0.1	μAdc
ON CHARACTERISTICS				
DC Current Gain	h _{FE}	25 40 40		_
DYNAMIC CHARACTERISTICS				
Current-Gain — Bandwidth Product (I _C = 10 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	f⊤	50	_	MHz
Feedback Capacitance (V _{CB} = 20 Vdc, I _E = 0, f = 1.0 MHz)	C _{re}	_	3.0	pF
Collector-Emitter Saturation Voltage (I _C = 20 mAdc, I _B = 2.0 mAdc)	V _{CE(sat)}	_	0.5	Vdc
Base-Emitter Saturation Voltage ($I_C = 20 \text{ mAdc}$, $I_B = 2.0 \text{ mAdc}$)	V _{BE(sat)}	_	0.9	Vdc

^{2.} Pulse Test Conditions, t_p = 300 μ s, δ 0.02.

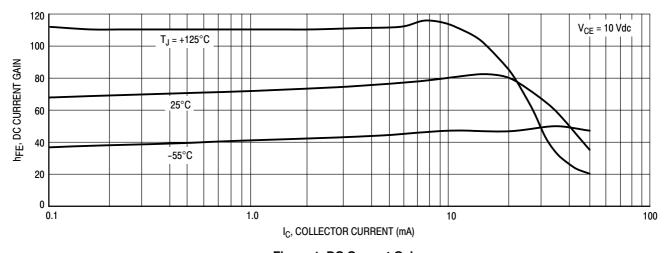


Figure 1. DC Current Gain

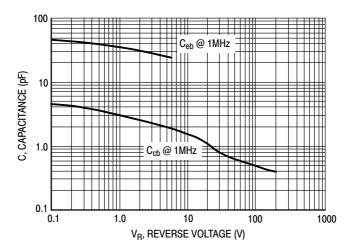
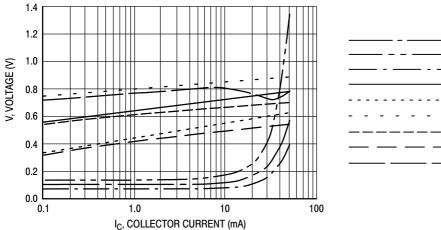
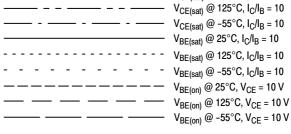


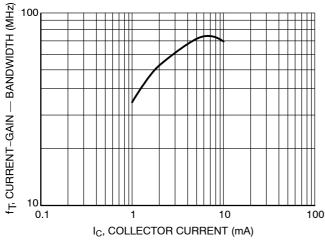
Figure 2. Capacitance





 $V_{CE(sat)}$ @ 25°C, $I_C/I_B = 10$

Figure 3. "ON" Voltages



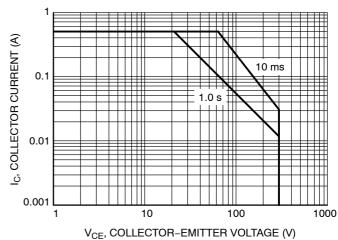


Figure 4. Current Gain Bandwidth Product

Figure 5. Safe Operating Area

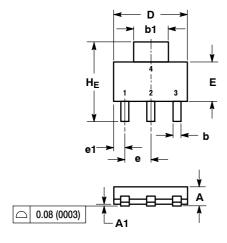
ORDERING INFORMATION

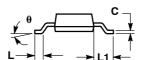
Device	Package	Shipping [†]
PZTA42T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE N





NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCH.

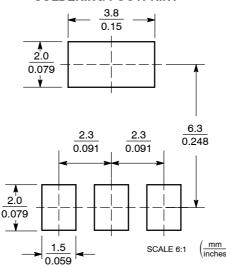
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1:

PIN 1. BASE

- 2. COLLECTOR
- B. EMITTER
- 4. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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